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A
E. Willis
6-24-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Iwasaki, Y.

SERIAL No. Unassigned

EXAMINER: Unassigned

FILED: Herewith

GROUP NO.: Unassigned

TITLE: BLADE-LIKE CONNECTING NEEDLE

Attorney Docket No.: 40010349-02

Commissioner For Patents
Washington, D.C. 20231

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20231, on

February 12, 2002
(Date of Deposit).

Allison Berkman
Name

Allison Berkman
Signature

PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as set forth below.

In The Abstract of the Disclosure

Please amend the Abstract of the Disclosure as follows:

A1

A blade-like connecting needle for measuring a semiconductor wafer has an increased capability for measuring a small current and also has stable characteristics. The blade-like connecting needle includes a blade signal line for transmitting signal from the semiconductor wafer, a support insulator covering at least a portion of the blade signal line, a plurality of blade guard patterns disposed in or on the support insulator for electromagnetically shielding the blade signal line, and a probe supported on the support insulator and connected to the blade signal line. There are also disclosed processes of producing the blade-like connecting needle. A method for manufacturing a coaxial or hollow blade-like connecting needle is also provided.